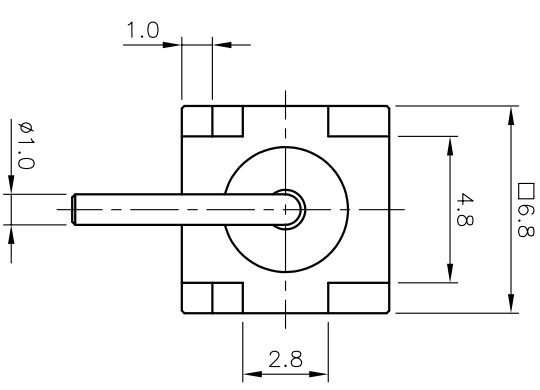
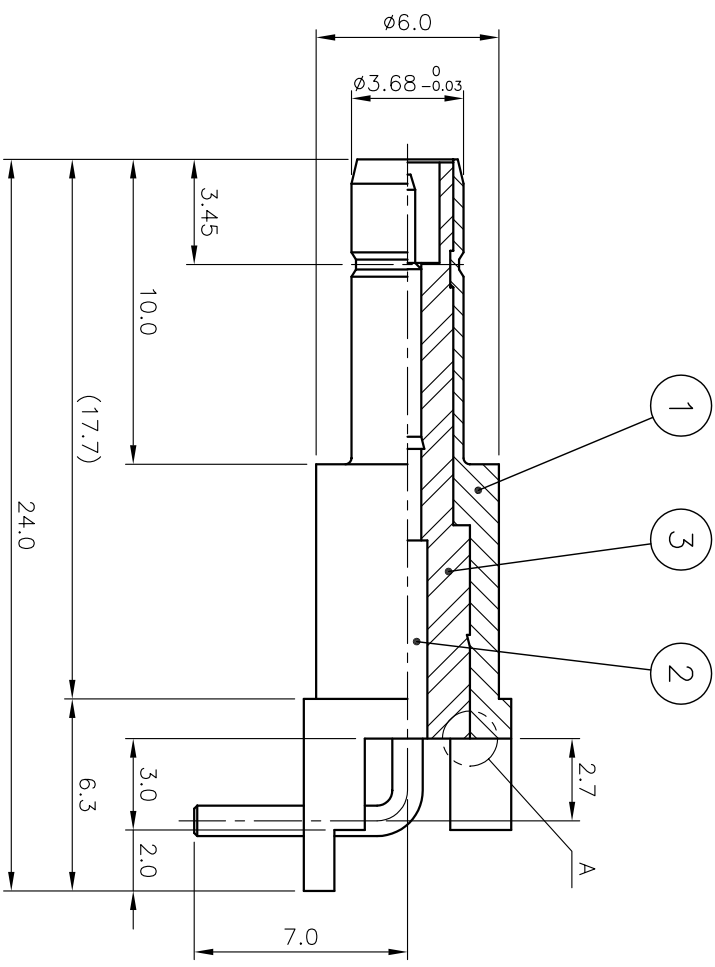


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
1R	Initial Registration		C.Y.H.	2011.05.27.



주 기

1. A부 BODY+TEFLON 조립 후 돌출을 엮을 것.
2. 제품의 외관에 이상이 없을 것.
3. 본 부품은 MS201-02를 만족 할 것.
4. 상대물과 삽입력과 이탈력
 - 삽입력 : 2~4kgf 이하
 - 이탈력 : 5~8kgf 이상

3	INSULATOR	1	TEFLON		DIN01923-N/1
2	CONTACT	1	MBSBD	Gold Plate	DC102470-5/1
1	BODY	1	MBSBD	Gold Plate	DB602933-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE
DATE		2011. 05. 27.			
APPROVED BY		Y.H.CHOI			
CHECKED BY					
DRAWN BY					
MATERIAL					
FINISH					
SCALE		UNIT			
4/1		mm			
A4					
DWG NO.		CN02686-7/1			
REVISION		I R	SHEET 1 of 1		

TOLERANCE		Decimal	DATE	
Angle		±0.1	2011. 05. 27.	
±1°		APPROVED BY Y.H.CHOI		
MATERIAL		CHECKED BY		
DRAWN BY				
FINISH				

		RF & MICROWAVE TECHNOLOGY	
KJ CONTECH CO., LTD.		Tel : 82-32-347-8015	
		Fax : 82-32-347-8017	

TITLE		SMB50 PCB JS-4R (pin r/a)	
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SMB50 PCB JS-4R (pin r/a)



RF & MICROWAVE TECHNOLOGY
Tel : 82-32-347-8015
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